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(19) **United States**(12) **Patent Application Publication** (10) **Pub. No.: US 2022/0352701 A1**  
KATO et al. (43) **Pub. Date: Nov. 3, 2022**(54) **METHOD OF MANUFACTURING WIRING  
MEMBER-EQUIPPED ADHEREND AND  
WIRING MEMBER-EQUIPPED ADHEREND**(30) **Foreign Application Priority Data**

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(2013.01); **H01B 7/40** (2013.01)(57) **ABSTRACT**

A method of manufacturing a wiring member equipped-adherend includes: a step (a) providing at least one heat generation body generating heat by induction heating between a wiring member including at least one wire-like transmission member and a fixation surface of an adherend; a step (b) providing a magnetic field generation source on a side of the adherend with respect to the wiring member; a step (c) generating a magnetic field fluctuating by the magnetic field generation source; a step (d) making the heat generation body generate heat by induction heating caused by the magnetic field fluctuating by the magnetic field generation source; and a step (e) fixing the wiring member to the fixation surface of the adherend by heat generation in the heat generation body.

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